

Day : Monday
Date: 3/22/2004


PALM INTRANET

Time: 15:07:23

Inventor Name Search Result

Your Search was:

Last Name = TAKEZAWA

First Name = HIROAKI

Application#	Patent#	Status	Date Filed	Title	Inventor Name 26
<u>10613042</u> KOPEK	Not Issued	030	07/07/2003	CONDUCTIVE ADHESIVE AGENT, PACKAGING STRUCTURE, AND METHOD FOR MANUFACTURING THE SAME STRUCTURE	TAKEZAWA, HIROAKI
<u>10409400</u>	Not Issued	092	04/07/2003	MOUNTING STRUCTURE FOR AN ELECTRONIC COMPONENT AND METHOD FOR PRODUCING THE SAME	TAKEZAWA, HIROAKI
<u>10309597</u>	6675474	150	12/03/2002	ELECTRONIC COMPONENT MOUNTED MEMBER AND REPAIR METHOD THEREOF	TAKEZAWA, HIROAKI
<u>10309596</u> KOPEK	Not Issued ⊖	092	12/03/2002	CONDUCTIVE ADHESIVE AND CONNECTION STRUCTURE USING THE SAME	TAKEZAWA, HIROAKI
<u>10309426</u>	6666994 /	150	12/03/2002	CONDUCTIVE ADHESIVE AND PACKAGING STRUCTURE USING THE SAME	TAKEZAWA, HIROAKI
<u>10030235</u>	Not Issued	030	03/26/2002	CONDUCTIVE ADHESIVE, APPARATUS FOR MOUNTING ELECTRONIC COMPONENT, AND METHOD FOR MOUNTING THE SAME	TAKEZAWA, HIROAKI
<u>09965768</u>	6569512 ✓	150	09/27/2001	MOUNTING STRUCTURE FOR AN ELECTRONIC COMPONENT AND METHOD FOR PRODUCING THE SAME	TAKEZAWA, HIROAKI
<u>09947353</u> KOPEK Parent	6620345	150	09/07/2001	CONDUCTIVE ADHESIVE AGENT, PACKAGING STRUCTURE, AND METHOD	TAKEZAWA, HIROAKI

				FOR MANUFACTURING THE SAME STRUCTURE	
<u>09898721</u>	<u>6524721</u> ✓	150	07/03/2001	CONDUCTIVE ADHESIVE AND PACKAGING STRUCTURE USING THE SAME	TAKEZAWA, HIROAKI
<u>09893106</u>	<u>6512183</u> ✓	150	06/27/2001	ELECTRONIC COMPONENT HAVING A CIRCUIT BOARD AND A THERMOPLASTIC INSULATING ADHESIVE INTERMEDIATE LAYER	TAKEZAWA, HIROAKI
<u>09889523</u>	<u>6510059</u> ✓	150	07/18/2001	CONDUCTIVE RESIN, ELECTRONIC MODULE USING CONDUCTIVE RESIN, AND METHOD OF MANUFACTURING ELECTRONIC MODULE	TAKEZAWA, HIROAKI
<u>09873461</u>	<u>6694613</u>	150	06/05/2001	A METHOD FOR PRODUCING A PRINTED CIRCUIT BOARD HAVING PROJECTION ELECTRODES	TAKEZAWA, HIROAKI
<u>09751621</u> KOPEL	<u>6521144</u>	150	12/29/2000	CONDUCTIVE ADHESIVE AND CONNECTION STRUCTURE USING THE SAME	TAKEZAWA, HIROAKI
<u>09747976</u>	Not Issued	041	12/27/2000	ELECTRONIC PART, AN ELECTRONIC PART MOUNTING ELEMENT AND AN PROCESS FOR MANUFACTURING SUCH THE ARTICLES	TAKEZAWA, HIROAKI
<u>09703286</u>	Not Issued	061	11/01/2000	METHOD OF MAKING AN ORGANIC ULTRA-THIN FILM	TAKEZAWA, HIROAKI
<u>09703284</u>	Not Issued	120	11/01/2000	METHOD OF MAKING AN ORGANIC ULTRA-THIN FILM	TAKEZAWA, HIROAKI
<u>09554502</u>	<u>6465082</u>	150	05/16/2000	STRESS RELAXATION ELECTRONIC PART, STRESS RELAXATION WIRING BOARD, AND STRESS RELAXATION ELECTRONIC PART MOUNTED BODY	TAKEZAWA, HIROAKI
<u>09547922</u>	<u>6429382</u>	150	04/11/2000	ELECTRICAL MOUNTING STRUCTURE HAVING AN ELUTION PREVENTIVE FILM	TAKEZAWA, HIROAKI

09519984	6376051	150	03/07/2000	MOUNTING STRUCTURE FOR AN ELECTRONIC COMPONENT AND METHOD FOR PRODUCING THE SAME	TAKEZAWA, HIROAKI
09125622	6495247	150	08/21/1998	FUNCTIONAL MEMBER HAVING MOLECULAR LAYER ON ITS SURFACE AND METHOD OF PRODUCING THE SAME	TAKEZAWA, HIROAKI
09107319	6207550	150	06/30/1998	METHOD FOR MOUNTING A SEMICONDUCTOR DEVICE ON A MULTILAYER SUBSTRATE	TAKEZAWA, HIROAKI
09106302	6300576	150	06/29/1998	PRINTED-CIRCUIT BOARD HAVING PROJECTION ELECTRODES AND METHOD FOR PRODUCING THE SAME	TAKEZAWA, HIROAKI
09056774	6488869	150	04/08/1998	CONDUCTIVE PASTE, ITS MANUFACTURING METHOD, AND PRINTED WIRING BOARD USING THE SAME	TAKEZAWA, HIROAKI
08992049	Not Issued	061	12/17/1997	ORGANIC ULTRA-THIN FILM AND METHOD FOR MAKING THE SAME	TAKEZAWA, HIROAKI
08980749	6203919	150	12/01/1997	INSULATING FILM AND METHOD FOR PREPARING THE SAME	TAKEZAWA, HIROAKI
08650747	5817190	150	05/20/1996	FLUX FOR SOFT SOLDERING	TAKEZAWA, HIROAKI

Inventor Search Completed: No Records to Display.

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Search Another: Inventor	<input type="text" value="TAKEZAWA"/>	<input type="text" value="HIROAKI"/>	<input type="button" value="Search"/>

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